



StructuredGround™ GB2B0304TPI-1 Telecom Grd Busbars, 0304, Copper, Tin-Plated

GB2B0304TPI-1

The GB2B0304TPI-1 Grounding Busbar meets BICSI and ANSI/TIA-607-D requirements for network systems grounding applications. Made of high conductivity copper and tin-plated to inhibit corrosion, comes pre-assembled with brackets and insulators attached for a quick installation. The insulators provide 600 V of insulation and use of Panduit self-laminating laser/ink jet labels to identify busbars.

Specifications

Sub Brand	StructuredGround™
Material	Copper
Overall Length (In.)	10
Overall Length (mm)	254
Overall Width (In.)	2
Overall Width (mm)	50.8
Overall Height (In.)	2.75
Overall Height (mm)	69.9
Stud Hole Size (In.)	0.44
Stud Hole Size (mm)	11.17
Finish/Coating	Tin-Plated
Overall Thickness (In.)	0.25
Overall Thickness (mm)	6.4
Standards Met	BICSI/TIA-607-D, cULus Listed for Grounding and Bonding Equipment
Application	Telecom/Data Center
Product Type	Grounding Busbar
Part Features	Available with a variety of hole pattern spacing options, Made of high conductivity copper and tin-plated to inhibit corrosion, Pre-assembled with brackets and insulators attached for quick installation

Packaging Detail

UPC	07498365926
Std. Pkg. Qty.	1
Std. Pkg. Volume (cf)	0.0030
Std. Ctn. Qty.	0
Std. Ctn. Volume (cf)	0.0000